

METHOD OF MANUFACTURING FINE METAL PARTICLES, SUBSTANCE
~~CONTAINING FINE METAL PARTICLES, AND PASTE SOLDER COMPOSITION~~

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CROSS-REFERENCE TO RELATED APPLICATIONS

5 This application claims priority to the United States Patent Application Serial
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BACKGROUND OF THE INVENTION

The present invention relates to a method of manufacturing fine metal particles such as solder particles, to a fine metal particles-containing substance containing such fine metal particles, and to a paste solder composition comprising such a fine metal particles-containing substance.

In recent years, concomitant with an increasing trend to multi-functionalize the wiring board of electronic devices as well as with an increasing trend of miniaturization, i.e. the reduction of the size and weight of electronic devices, a surface mounting technique has now been quickly advanced, so that it is now desired, for the purpose of realizing a high density packaging such as the surface mounting of electronic device, to develop a solder paste or other kinds of soldering materials and a soldering method, which are not